DOCUMENT CHANGE REQUEST

DCR number 517	Changes required for: General	Originator: S Jeffery - ESCC
Date: 2009/05/06	Date sent: 2009/05/06	Organisation: ESA/ESTEC
Status: IMPLEMENTED		

Title:	Transistors Silicon Switching PNP, based on type 2N3467		
Number:	5208/009	Issue:	2

Other documents affected:

Page:

See attachment

Paragraph:

See attachment

Original wording:

Proposed wording:

Update the Maximum Ratings table (see the attachment for details) so that this detail spec is clear, complete and the content and format is in-line with other detail specifications for similar Part Types.

Justification:

Improve the content and clarity of the spec.

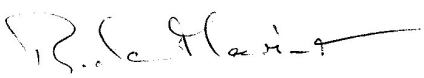
Attachments:

5208009_Issue_3_-_Draft_A.pdf, null

Modifications:

N/A

Approval signature:



Date signed:

2009-05-06

European Space Components Coordination

TRANSISTORS, SWITCHING, PNP

BASED ON TYPE 2N3467

ESCC Detail Specification No. 5208/009

as applicable

Issue ~~2~~ 3 - Draft A	~~October 2008~~

Document Custodian: European Space Agency - see https://escies.org

as applicable

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DOCUMENTATION CHANGE NOTICE

(Refer to https://escies.org for ESCC DCR content)

DCR No.	CHANGE DESCRIPTION
380	Specification up issued to incorporate editorial and technical changes per DCR.

tbd

At $T_{case} \leq +25°C$

see attached

Characteristics	Symbols	Maximum Ratings	Unit	Remarks
Collector-Base Voltage	V_{CBO}	-40	V	Over entire operating temperature range
Collector-Emitter Voltage	V_{CEO}	-40	V	
Emitter-Base Voltage	V_{EBO}	-5	V	
Collector Current	I_C	-1	A	Continuous
Power Dissipation	P_{tot} 1	1	W	At $T_{amb} \leq +25°C$
	P_{tot} 2	5	W	~~Note 1~~
Operating Temperature Range	T_{op}	-65 to +200	°C	Note 1
Storage Temperature Range	T_{stg}	-65 to +200	°C	Note 1
Soldering Temperature	T_{sol}	+265	°C	Note 2

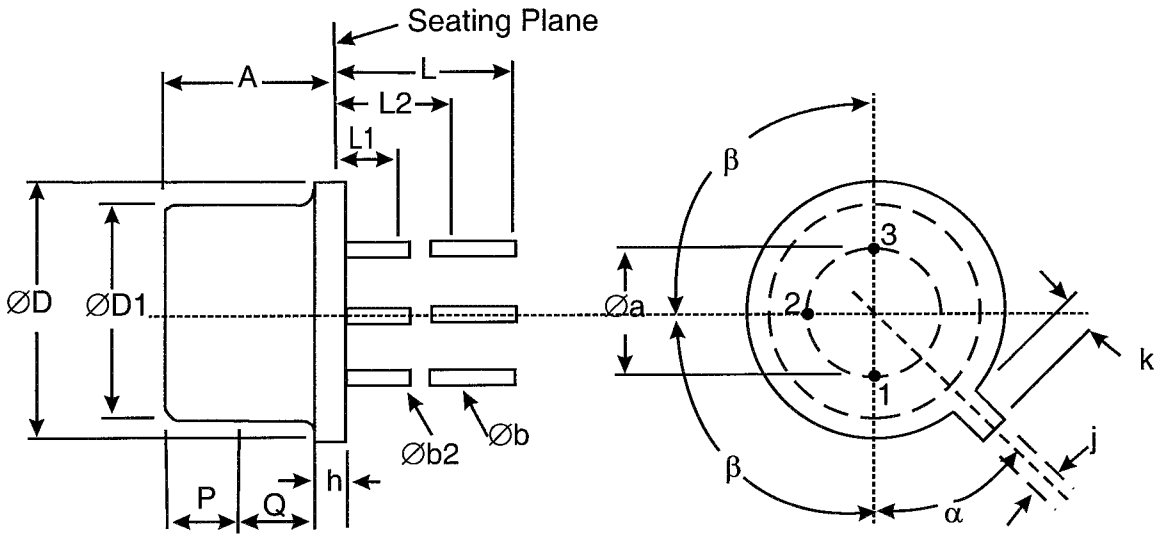
NOTES:

~~1. For $T_{amb} > +25°C$, derate linearly to 0W at +200°C~~

1. For Variants with tin-lead plating or hot solder dip lead finish all testing performed at $T_{amb} > +125°C$ shall be carried out in a 100% inert atmosphere.
2. Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.

1.6 PHYSICAL DIMENSIONS AND TERMINAL IDENTIFICATION

1.6.1 Metal Can Package (TO-39) - 3 lead



Symbols	Dimensions mm		Notes
	Min	Max	
Øa	4.83	5.35	
A	6	6.6	
Øb	0.4	0.533	2, 3
Øb2	0.4	0.483	2, 3

Thermal Resistance, Junction-to-Ambient	$R_{th(j-a)}$	175	°C/W	
Thermal Resistance, Junction-to-Case	$R_{th(j-c)}$	30	°C/W	